



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN#20201112000.1
Qualification of an additional Substrate Manufacturing
Subcontractor for select devices
Change Notification / Sample Request

Date: November 19, 2020
To: Newark/Farnell PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The proposed first ship date is indicated on page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Team (PCN_ww_admin_team@list.ti.com). For sample requests or sample related questions, contact your field sales representative.

Sincerely,

PCN Team
SC Business Services

2020112000.1
Change Notification / Sample Request
Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TPS82740ASIPT	null
TPS82740BSIPT	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20201112000.1		PCN Date:	Nov 19, 2020																					
Title:	Qualification of an additional Substrate Manufacturing Subcontractor for select devices																								
Customer Contact:	PCN Manager	Dept:	Quality Services																						
Proposed 1st Ship Date:	Feb 19, 2021	Estimated Sample Availability:	Date provided at sample request																						
Change Type:																									
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site																				
<input checked="" type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material																				
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process																				
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site																				
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials																				
				<input type="checkbox"/>	Wafer Fab Process																				
PCN Details																									
Description of Change:																									
<p>TI is qualifying an additional substrate manufacturing subcontractor (ACCESS) for the devices in the product affected section shown below. Assembly site origin (ASO) will remain unchanged. Construction differences are as follows:</p>																									
<table border="1"> <thead> <tr> <th></th> <th>Current (ATNS)</th> <th>New (ACCESS)</th> </tr> </thead> <tbody> <tr> <td>Substrate Material</td> <td>R1551W</td> <td>6785GTK</td> </tr> <tr> <td>Solder mask</td> <td>XV501T</td> <td>SR7300G</td> </tr> <tr> <td>Adhesive</td> <td>AD222</td> <td>N/A</td> </tr> <tr> <td>Cavity Filler</td> <td>N/A</td> <td>ABF GX-T31</td> </tr> <tr> <td>L1/L2 metal</td> <td>23um Cu</td> <td>15um Cu</td> </tr> <tr> <td>Surface Finish</td> <td>OSP</td> <td>OSP</td> </tr> </tbody> </table>						Current (ATNS)	New (ACCESS)	Substrate Material	R1551W	6785GTK	Solder mask	XV501T	SR7300G	Adhesive	AD222	N/A	Cavity Filler	N/A	ABF GX-T31	L1/L2 metal	23um Cu	15um Cu	Surface Finish	OSP	OSP
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Reason for Change:																									
Continuity of Supply																									
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):																									
None																									
Anticipated impact on Material Declaration																									
<input type="checkbox"/>	No Impact to the Material Declaration	<input checked="" type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained at the site link below http://www.ti.com/quality/docs/materialcontentsearch.tsp																						
Changes to product identification resulting from this PCN:																									
N/A																									
Product Affected:																									
TPS82740ASIPR	TPS82740ASIPT	TPS82740BSIPR	TPS82740BSIPT																						

Qualification Report

Approve Date 16-Oct-2020

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TPS82740ASIPR	QBS Process Reference: TPS82130PSIL
HAST	Biased HAST, 110C/85%RH	264 Hours	1/77/0	2/231/0
HTSL	High Temp Storage Bake 150C	1000 Hours	QBS	3/231/0
SD	Pb Free Surface Mount Solderability	4 hour @ 155C aging	1/22/0	-
TC	Temperature Cycle, -55/125C	700 Cycles	1/77/0	3/239/0
UHAST	Unbiased HAST 110C/85%RH	264 Hours	-	3/231/0
UHAST	Unbiased HAST 130C/85%RH	96 hours	1/77/0	-

- QBS: Qual By Similarity

- Qual Device TPS82740xSIPR devices are qualified at LEVEL2-260CG

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
WW PCN Team	PCN_ww_admin_team@list.ti.com

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